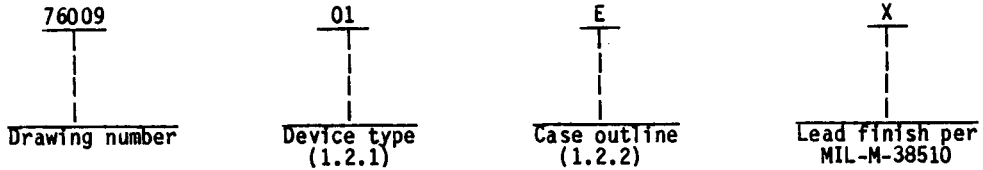




1. SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device type. The device type shall identify the circuit function as follows:

Device type	Generic number	Circuit
01	54LS191	Synchronous up/down counter with down/up mode control

1.2.2 Case outlines. The case outlines shall be as designated in MIL-M-38510, appendix C and as follows:

Outline letter	Case outline
E	D-2 (16-lead, 1/4" x 7/8"), dual-in-line package
F	F-5 (16-lead, 1/4" x 3/8"), flat package
2	C-2 (20-terminal, .350" x .350") square chip carrier package

1.3 Absolute maximum ratings.

Supply voltage range - - - - -	-0.5 V dc to +7.0 V dc
Input voltage range- - - - -	-1.5 V dc at -18 mA to +5.5 V dc
Storage temperature range- - - - -	-65°C to +150°C
Maximum power dissipation (P <sub>D</sub> ) 1/- - - - -	192 mW
Lead temperature (soldering, 10 seconds) - - - - -	+300°C
Thermal resistance, junction-to-case (θ <sub>JC</sub> ) - - - - -	See MIL-M-38510, appendix C
Junction temperature (T <sub>J</sub> )- - - - -	+175°C

1.4 Recommended operating conditions.

Supply voltage (V <sub>CC</sub> ) - - - - -	4.5 V dc minimum to 5.5 V dc maximum
Minimum high level input voltage (V <sub>IH</sub> ) - - - - -	2.0 V dc
Maximum low level input voltage (V <sub>IL</sub> ) - - - - -	0.7 V dc
Case operating temperature range (T <sub>C</sub> ) - - - - -	-55°C to +125°C

1/ Must withstand the added P<sub>D</sub> due to short circuit test (e.g., I<sub>OS</sub>).

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2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Truth table. The truth table shall be as specified on figure 2.

3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.5 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.

3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.

3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C < T <sub>C</sub> < +125°C unless otherwise specified	Group A subgroups	Limits		Units
				Min	Max	
High level output voltage	V <sub>OH</sub>	V <sub>CC</sub> = 4.5 V; I <sub>OH</sub> = -400 μA V <sub>IN</sub> = 0.7 V or 2.0 V	1, 2, 3	2.5		V
Low level output voltage	V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V; I <sub>OL</sub> = 4 mA V <sub>IN</sub> = 0.7 V or 2.0 V	1, 2, 3		0.4	V
Input clamp voltage	V <sub>IC</sub>	V <sub>CC</sub> = 4.5 V; I <sub>IN</sub> = -18 mA; T <sub>C</sub> = +25°C	1		-1.5	V
High level input current, enable input	I <sub>IH1</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 2.7 V	1, 2, 3		60	μA
High level input current, other inputs	I <sub>IH2</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 2.7 V	1, 2, 3		20	μA
High level input current, enable input	I <sub>IH3</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 5.5 V	1, 2, 3		0.3	mA
High level input current, other inputs	I <sub>IH4</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 5.5 V	1, 2, 3		0.1	mA
Low level input current, enable input	I <sub>IL1</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0.4 V	1, 2, 3		-1.2	mA
Low level input current, other inputs	I <sub>IL2</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0.4 V	1, 2, 3		-0.4	mA
Short circuit output current	I <sub>OS</sub>	V <sub>CC</sub> = 5.5 V <u>1/</u>	1, 2, 3	-20	-100	mA
Supply current	I <sub>CC</sub>	V <sub>CC</sub> = 5.5 V	1, 2, 3		35	mA
Functional tests		See 4.4.1d	7			

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T <sub>C</sub> < +125°C unless otherwise specified	Group A subgroups	Limits		Units
				Min	Max	
Maximum clock frequency <u>2/</u>	f <sub>MAX</sub>	V <sub>CC</sub> = 5.0 V R <sub>L</sub> = 2 kΩ ±5%	C <sub>L</sub> = 15 pF ±10%	9	20	MHz
				10, 11	12	MHz
			C <sub>L</sub> = 50 pF ±10%	9	15	MHz
				10, 11	10	MHz
Propagation delay time, high to low level <u>2/</u> load to Q <sub>A</sub> , Q <sub>B</sub> , Q <sub>C</sub> , Q <sub>D</sub>	t <sub>PHL1</sub>		C <sub>L</sub> = 15 pF ±10%	9	50	ns
				10, 11	70	ns
			C <sub>L</sub> = 50 pF ±10%	9	55	ns
				10, 11	77	ns
Propagation delay time, low to high level <u>2/</u> load to Q <sub>A</sub> , Q <sub>B</sub> , Q <sub>C</sub> , Q <sub>D</sub>	t <sub>PLH1</sub>		C <sub>L</sub> = 15 pF ±10%	9	33	ns
				10, 11	46	ns
			C <sub>L</sub> = 50 pF ±10%	9	38	ns
				10, 11	53	ns
Propagation delay time, high to low level <u>2/</u> data A, B, C, D to Q <sub>A</sub> , Q <sub>B</sub> , Q <sub>C</sub> , Q <sub>D</sub>	t <sub>PHL2</sub>		C <sub>L</sub> = 15 pF ±10%	9	40	ns
				10, 11	56	ns
			C <sub>L</sub> = 50 pF ±10%	9	45	ns
				10, 11	63	ns
Propagation delay time, low to high level <u>2/</u> data A, B, C, D to Q <sub>A</sub> , Q <sub>B</sub> , Q <sub>C</sub> , Q <sub>D</sub>	t <sub>PLH2</sub>		C <sub>L</sub> = 15 pF ±10%	9	32	ns
				10, 11	45	ns
			C <sub>L</sub> = 50 pF ±10%	9	37	ns
				10, 11	52	ns
Propagation delay time, high to low level <u>2/</u> clock to ripple clock	t <sub>PHL3</sub>		C <sub>L</sub> = 15 pF ±10%	9	24	ns
				10, 11	34	ns
			C <sub>L</sub> = 50 pF ±10%	9	29	ns
				10, 11	41	ns

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T <sub>C</sub> < +125°C unless otherwise specified	Group A subgroups	Limits		Units
				Min	Max	
Propagation delay time, low to high level clock to ripple clock <u>2/</u>	t <sub>PLH3</sub>	V <sub>CC</sub> = 5.0 V R <sub>L</sub> = 2 kΩ ±5%	C <sub>L</sub> = 15 pF ±10%	9	20	ns
				10, 11	28	ns
			C <sub>L</sub> = 50 pF ±10%	9	25	ns
				10, 11	35	ns
			C <sub>L</sub> = 15 pF ±10%	9	36	ns
				10, 11	50	ns
Propagation delay time, high to low level clock to Q <sub>A</sub> , Q <sub>B</sub> , Q <sub>C</sub> , Q <sub>D</sub> <u>2/</u>	t <sub>PHL4</sub>		C <sub>L</sub> = 15 pF ±10%	9	36	ns
				10, 11	50	ns
			C <sub>L</sub> = 50 pF ±10%	9	41	ns
				10, 11	57	ns
			C <sub>L</sub> = 15 pF ±10%	9	24	ns
				10, 11	34	ns
Propagation delay time, low to high level clock to Q <sub>A</sub> , Q <sub>B</sub> , Q <sub>C</sub> , Q <sub>D</sub> <u>2/</u>	t <sub>PLH4</sub>		C <sub>L</sub> = 15 pF ±10%	9	24	ns
				10, 11	34	ns
			C <sub>L</sub> = 50 pF ±10%	9	29	ns
				10, 11	41	ns
			C <sub>L</sub> = 15 pF ±10%	9	52	ns
				10, 11	73	ns
Propagation delay time, high to low level clock to maximum <u>2/</u>	t <sub>PHL5</sub>		C <sub>L</sub> = 15 pF ±10%	9	52	ns
				10, 11	73	ns
			C <sub>L</sub> = 50 pF ±10%	9	57	ns
				10, 11	80	ns
			C <sub>L</sub> = 15 pF ±10%	9	42	ns
				10, 11	59	ns
Propagation delay time, low to high level clock to maximum <u>2/</u>	t <sub>PLH5</sub>		C <sub>L</sub> = 15 pF ±10%	9	42	ns
				10, 11	59	ns
			C <sub>L</sub> = 50 pF ±10%	9	47	ns
				10, 11	66	ns
			C <sub>L</sub> = 15 pF ±10%	9	45	ns
				10, 11	63	ns
Propagation delay time, high to low level down/up to ripple clock <u>2/</u>	t <sub>PHL6</sub>		C <sub>L</sub> = 15 pF ±10%	9	45	ns
				10, 11	63	ns
			C <sub>L</sub> = 50 pF ±10%	9	50	ns
				10, 11	70	ns
			C <sub>L</sub> = 15 pF ±10%	9	45	ns
				10, 11	63	ns

See footnotes at end of table.

<b>MILITARY DRAWING</b> DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 76009
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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T <sub>C</sub> < +125°C unless otherwise specified	Group A subgroups	Limits		Units
				Min	Max	
Propagation delay time, low to high level <sup>2/</sup> down/up to ripple clock	t <sub>PLH6</sub>	V <sub>CC</sub> = 5.0 V R <sub>L</sub> = 2 kΩ ±5%	C <sub>L</sub> = 15 pF ±10%	9	45	ns
				10, 11	63	ns
			C <sub>L</sub> = 50 pF ±10%	9	50	ns
				10, 11	70	ns
Propagation delay time, high to low level <sup>2/</sup> down/up to maximum	t <sub>PHL7</sub>		C <sub>L</sub> = 15 pF ±10%	9	33	ns
				10, 11	46	ns
			C <sub>L</sub> = 50 pF ±10%	9	38	ns
				10, 11	53	ns
Propagation delay time, low to high level <sup>2/</sup> down/up to maximum	t <sub>PLH7</sub>		C <sub>L</sub> = 15 pF ±10%	9	33	ns
				10, 11	46	ns
			C <sub>L</sub> = 50 pF ±10%	9	38	ns
				10, 11	53	ns
Propagation delay time, high to low level <sup>2/</sup> enable to ripple clock	t <sub>PHL8</sub>		C <sub>L</sub> = 15 pF ±10%	9	33	ns
				10, 11	46	ns
			C <sub>L</sub> = 50 pF ±10%	9	38	ns
				10, 11	53	ns
Propagation delay time, low to high level <sup>2/</sup> enable to ripple clock	t <sub>PLH8</sub>		C <sub>L</sub> = 15 pF ±10%	9	33	ns
				10, 11	46	ns
			C <sub>L</sub> = 50 pF ±10%	9	38	ns
				10, 11	53	ns

1/ Not more than one output should be shorted at a time, and the duration of the short circuit condition should not exceed one second.

2/ Propagation delay time testing and maximum clock frequency testing may be performed using either C<sub>L</sub> = 15 pF or C<sub>L</sub> = 50 pF. However, the manufacturer must certify and guarantee that the microcircuits meet the switching test limits specified for a 50 pF load.

**MILITARY DRAWING**

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SIZE  
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DWG NO.

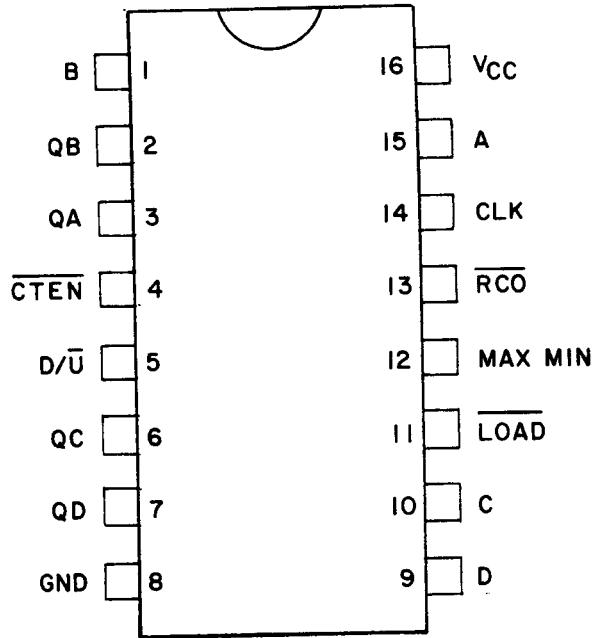
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Cases E and F



Case 2

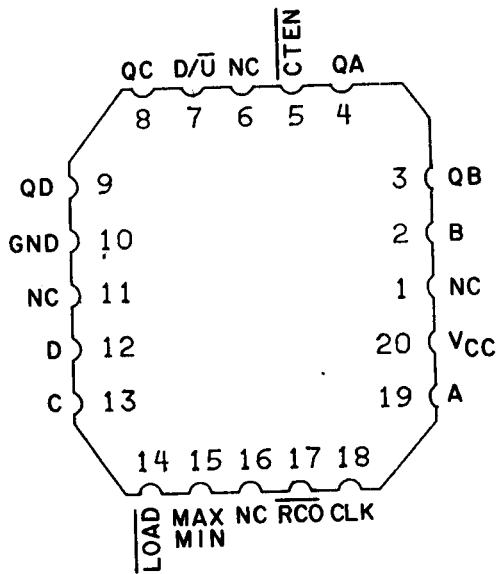


FIGURE 1. Terminal connections.

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Up count	Output				RIP CLK	Down count	Output				RIP CLK
	Q <sub>D</sub>	Q <sub>C</sub>	Q <sub>B</sub>	Q <sub>A</sub>			Q <sub>A</sub>	Q <sub>B</sub>	Q <sub>C</sub>	Q <sub>D</sub>	
0	L	L	L	L	H	15	H	H	H	H	H
1	L	L	L	H	H	14	L	H	H	H	H
2	L	L	H	L	H	13	H	L	H	H	H
3	L	L	H	H	H	12	L	L	H	H	H
4	L	H	L	L	H	11	H	H	L	H	H
5	L	H	L	H	H	10	L	H	L	H	H
6	L	H	H	L	H	9	H	L	L	H	H
7	L	H	H	H	H	8	L	L	L	H	H
8	H	L	L	L	H	7	H	H	H	L	H
9	H	L	L	H	H	6	L	H	H	L	H
10	H	L	H	L	H	5	H	L	H	L	H
11	H	L	H	H	H	4	L	L	H	L	H
12	H	H	L	L	H	3	H	H	L	L	H
13	H	H	L	H	H	2	L	H	L	L	H
14	H	H	H	L	H	1	H	L	L	L	H
15	H	H	H	H	L	0	L	L	L	L	L

H = high level, L = low level

H = high level, L = low level

FIGURE 2. Truth table.

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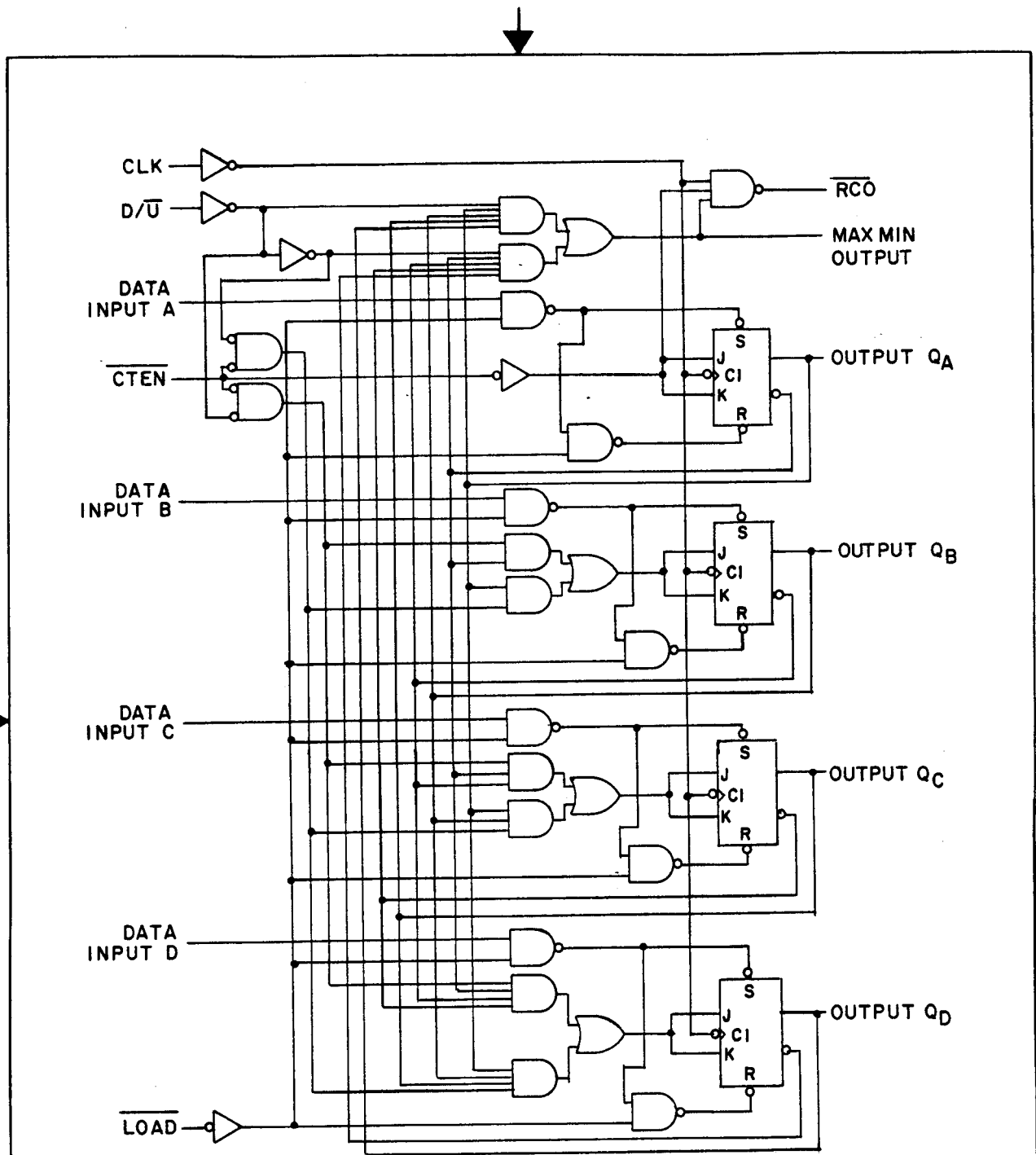


FIGURE 3. Logic diagram.

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3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

#### 4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test (method 1015 of MIL-STD-883).

(1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2)  $T_A = +125^\circ\text{C}$ , minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

##### 4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 4, 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.

c. Subgroup 4 ( $C_{IN}$  measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.

##### 4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test (method 1005 of MIL-STD-883) conditions:

(1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2)  $T_A = +125^\circ\text{C}$ , minimum.

(3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*, 2, 3, 9
Group A test requirements (method 5005)	1, 2, 3, 7, 9
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3
Additional electrical subgroups for group C periodic inspections	10, 11**

\* PDA applies to subgroup 1.

\*\* Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 Replaceability. Replaceability is determined as follows:

- a. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- b. When a QPL source is established, the part numbered device specified in this drawing will be replaced by the microcircuit identified as part number M38510/31509B--.

6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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6.4 Approved sources of supply. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1/</u>	Replacement military specification part number
7600901EX <u>2/</u>	04713 18324 01295	54LS191/BEAJC 54LS191/BEA SNJ54LS191J	M38510/31509BEX
7600901FX <u>2/</u>	04713 18324 01295	54LS191/BFAJC 54LS191/BFA SNJ54LS191W	M38510/31509BFX
76009012X <u>2/</u>	04713 18324 01295	54LS191M/B2AJC 54LS191/B2A SNJ54LS191EK	M38510/31509B2X

- 1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 2/ Inactive for new design. Use QPL-38510 product.

Vendor CAGE number

Vendor name and address

04713

Motorola Incorporated  
7402 South Price Road  
Tempe, AZ 85283

18324

Signetics Corporation  
4130 South Market Court  
Sacramento, CA 95834

01295

Texas Instruments Inc.  
P.O. Box 6448  
Midland, TX 79701

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